

## N-Channel 60 V(D-S) MOSFET

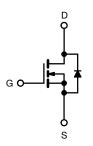
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)}(\Omega)$	V <sub>GS</sub> = 10 V 0.072			
Q <sub>g</sub> max. (nC)	25			
Q <sub>gs</sub> (nC)	5.8			
Q <sub>gd</sub> (nC)	11			
Configuration	Single			

#### **FEATURES**

- Dynamic dV/dt rating
- Fast switching
- Ease of paralleling Simple drive requirements







N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_C = 25$ °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	60	V		
Gate-Source Voltage			$V_{GS}$	± 20	- V	
Continuous Drain Current	$V_{GS}$ at 10 V $\frac{T_C = 25^{\circ}}{T_C = 100^{\circ}}$			20		
Continuous Drain Current	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	- I <sub>D</sub>	12	Α	
Pulsed Drain Current a			I <sub>DM</sub>	68	1	
Linear Derating Factor			0.40	W/°C		
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	100	mJ	
Maximum Power Dissipation T <sub>C</sub> = 25 °C		$P_{D}$	60	W		
Peak Diode Recovery dV/dt <sup>c</sup>			dV/dt	4.5	V/ns	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Soldering Recommendations (Peak temperature) d	for 10 s			300	7	
Mounting Torque	6 20 or l	M2 corour		10	lbf ⋅ in	
Mounting Torque	6-32 or M3 screw			1.1	N·m	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b.  $V_{DD}$  = 25 V, starting  $T_J$  = 25 °C, L = 403  $\mu$ H,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 17 A (see fig. 12).
- c.  $I_{SD} \leq 17$  A,  $dI/dt \leq 140$  A/µs,  $V_{DD} \leq V_{DS}$ ,  $T_{J} \leq 175$  °C.
- d. 1.6 mm from case.

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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62		
Case-to-Sink, Flat, Greased Surface	R <sub>thCS</sub>	0.50	-	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	2.5		

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static				1	1		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I <sub>D</sub> = 1 mA		0.061	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	- V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.0	-	3.0	V
Gate-Source Leakage	I <sub>GSS</sub>	,	V <sub>GS</sub> = ± 20 V		-	± 100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		= 60 V, V <sub>GS</sub> = 0 V , V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C	-	-	25 250	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10 A <sup>b</sup>	-	0.072	-	Ω
Forward Transconductance	9 <sub>fs</sub>	$V_{DS}$	= 25 V, I <sub>D</sub> = 10 A	5.5	-	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,	-	640	-	pF
Output Capacitance	C <sub>oss</sub>		$V_{DS} = 25 \text{ V},$	-	360	-	
Reverse Transfer Capacitance	$C_{rss}$	f = 1.	.0 MHz, see fig. 5	-	79	-	
Total Gate Charge	$Q_g$			-	-	25	
Gate-Source Charge	$Q_{gs}$	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 17 A, V <sub>DS</sub> = 48 V, see fig. 6 and 13 <sup>b</sup>	-	-	5.8	nC
Gate-Drain Charge	Q <sub>gd</sub>	1			-	11	
Turn-On Delay Time	t <sub>d(on)</sub>			-	13	-	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 30 V, $I_{D}$ = 17 A, $R_{g}$ = 18 $\Omega$ , $R_{D}$ = 1.7 $\Omega$ , see fig. 10 <sup>b</sup>		-	58	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>			-	25		
Fall Time	t <sub>f</sub>			-	42	-	
Internal Drain Inductance	L <sub>D</sub>	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	الم
Internal Source Inductance	L <sub>S</sub>			-	7.5	-	- nH
Drain-Source Body Diode Characteristic	s				•		
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	20	А
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			-	-	68	^
Body Diode Voltage	$V_{SD}$	T <sub>J</sub> = 25 °C	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 17 A, V <sub>GS</sub> = 0 V <sup>b</sup>		-	1.5	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = 17 A, dl/dt = 100 A/μs		-	88	180	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			-	0.29	0.64	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic tu	rn-on time is negligible (turn	on is do	ninated b	y L <sub>S</sub> and	L <sub>D</sub> )

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq 300~\mu s$ ; duty cycle  $\leq 2~\%$ .



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

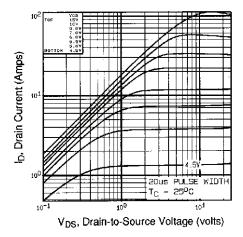


Fig. 1 - Typical Output Characteristics,  $T_C = 25$  °C

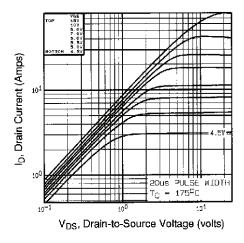


Fig. 2 - Typical Output Characteristics,  $T_C$  = 175  $^{\circ}C$ 

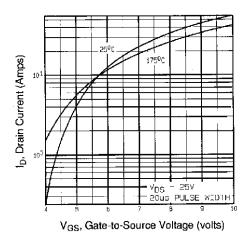


Fig. 3 - Typical Transfer Characteristics

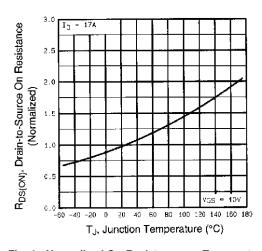


Fig. 4 - Normalized On-Resistance vs. Temperature

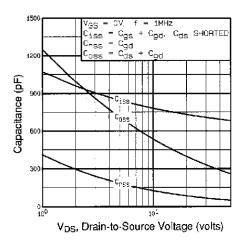


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

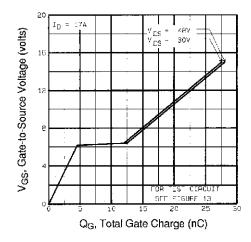


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



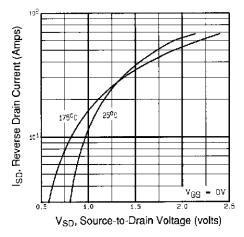


Fig. 7 - Typical Source-Drain Diode Forward Voltage

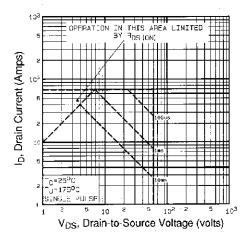


Fig. 8 - Maximum Safe Operating Area

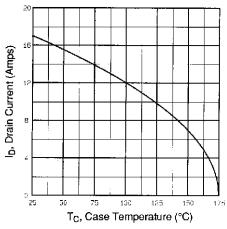


Fig. 9 - Maximum Drain Current vs. Case Temperature

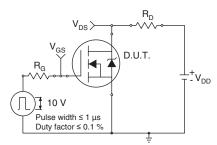


Fig. 10a - Switching Time Test Circuit

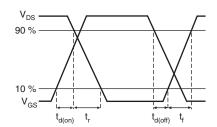


Fig. 10b - Switching Time Waveforms

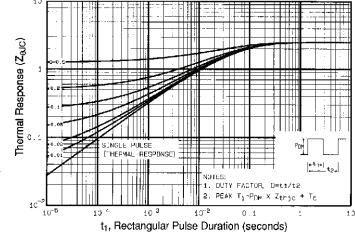
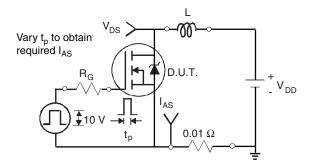


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case





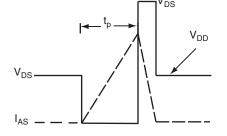


Fig. 12a - Unclamped Inductive Test Circuit

Fig. 12b - Unclamped Inductive Waveforms

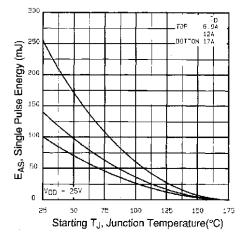


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

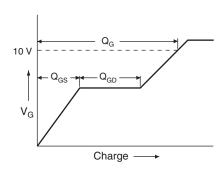


Fig. 13a - Basic Gate Charge Waveform

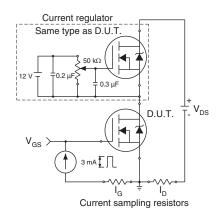
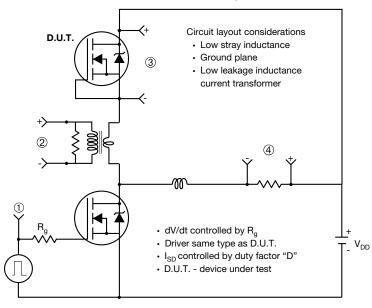


Fig. 13b - Gate Charge Test



#### Peak Diode Recovery dV/dt Test Circuit



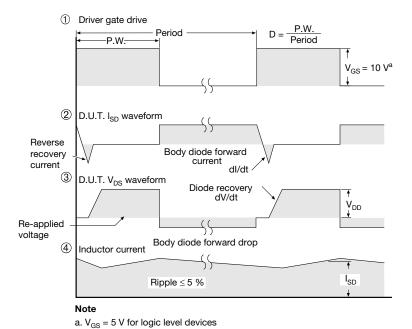
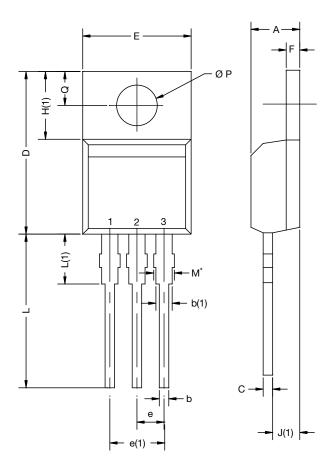


Fig. 14 - For N-Channel



## **TO-220**



DIM.	MILLIN	METERS	INCHES		
DIN.	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

# DWG: 6031

 $\bullet~M^{\star}=0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP BXP7N65D BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L
BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
BSO203SP BSO211P IPA60R230P6 IPA60R460CE